April 2006



FS8S0765RCB Fairchild Power Switch (FPS™)

Features

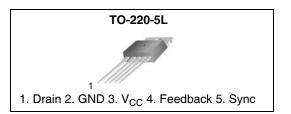
- Burst Mode Operation to Reduce the Power Consumption in the Standby Mode
- External pin for Synchronization and Soft Start
- Wide Operating Frequency Range up to 150kHz
- Low Start-up Current (Max:80µA)
- Low Operating Current (Max:15mA)
- Pulse by Pulse Current Limiting
- Over-Voltage Protection (Auto Restart Mode)
- Overload Protection (Auto Restart Mode)
- Abnormal Over-Current Protection (Auto Restart Mode)
- Internal Thermal Shutdown (Auto Restart Mode)
- Under-Voltage Lockout
- Internal High-Voltage SenseFET

Description

FS8S0765RCB is a Fairchild Power Switch (FPS) that is specially designed for off-line SMPS of CRT monitors with minimal external components. This device is a current mode pulse-width modulated (PWM) controller combined with a high-voltage power SenseFET in a single package. The PWM controller features integrated oscillator to be synchronized with the external sync signal, under-voltage lockout, optimized gate driver, temperature compensated precise current sources for the loop compensation. This device also includes various fault-protection, circuits such as over voltage protection, overload protection, abnormal over current protection and over-temperature protection, Compared with a discrete MOSFET and PWM controller solution, FPS can reduce total cost, component count, size, weight, while increasing efficiency, productivity, and system reliability. This device is well suited for the cost-effective monitor power supply.

Applications

SMPS for Monitor



Ordering Information

Product Number	Package	Marking Code	BV _{DSS}	R _{DS(ON)}
FS8S0765RCBTU ⁽¹⁾	TO-220-5L	8S0765RC	650V	1.6Ω
FS8S0765RCBYDTU (2)	TO-220-5L (Forming)	030705HC		

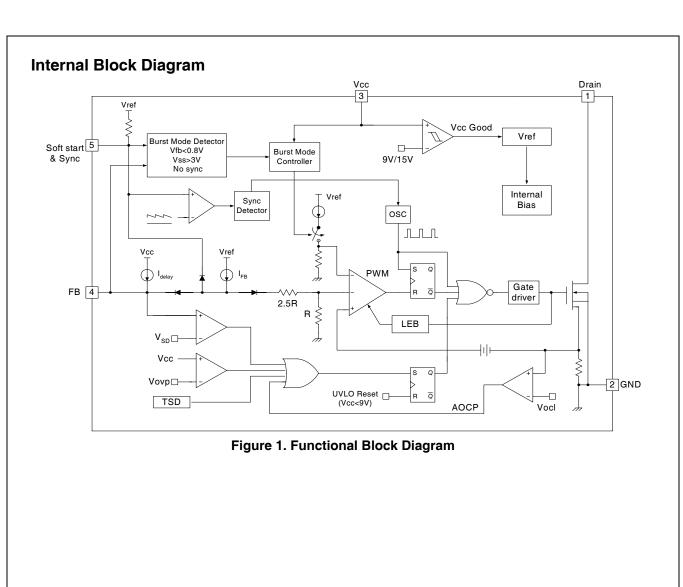
Notes:

1. TU: Non Forming Type

2. YDTU: Forming Type

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Pin Configuration

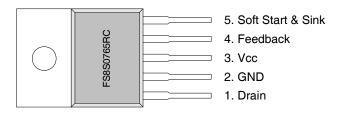


Figure 2. Pin Configuration (Top View)

Pin Definitions

Pin Number	Pin Name	Pin Function Description
1	Drain	SenseFET Drain. High voltage power SenseFET drain connection. This pin is designed to drive the transformer directly.
2	GND	Ground. Control ground and the SenseFET source.
3	Vcc	Supply Voltage. Supply input. This pin provides internal operating current for both start-up and steady-state operation.
4	Feedback	Feedback. Internally connected to the inverting input of the PWM comparator. For stable operation, a capacitor should be placed between this pin and GND. If the voltage of this pin reaches 7.5V, the overload protection is activated, resulting in shutdown of FPS.
5	Soft Start & Sync	Soft Start and Sync. For soft-start and synchronization to the external sync signal.

Absolute Maximum Ratings

The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table defines the conditions for actual device operation. ($T_A = 25^{\circ}C$, unless otherwise specified)

Symbol	Parameter	Value	Unit
V _{DSS}	Drain-Source (GND) Voltage (1)	650	V
V _{DGR}	Drain-Gate Voltage (R_{GS} =1M Ω)	650	V
V _{GS}	Gate-Source (GND) Voltage	±30	V
I _{DM}	Drain Current Pulsed ⁽²⁾	28	A _{DC}
E _{AS}	Single Pulsed Avalanche Energy ⁽³⁾	370	mJ
I _{AS}	Single Pulsed Avalanche Current ⁽⁴⁾	17	А
۱ _D	Continuous Drain Current (Tc = 25°C)	7	A _{DC}
۱ _D	Continuous Drain Current (Tc=100°C)	4.5	A _{DC}
V _{CC}	Supply Voltage	40	V
V _{FB}	Input Voltago Pango	-0.3 to Vcc	V
V _{S_S}	 Input Voltage Range 	-0.3 to 10	V
P _D (Watt H/S)	Total Dawar Dissination	145	W
Derating	 Total Power Dissipation 	1.16	W/°C
Т _ј	Operating Junction Temperature	+150	°C
T _A	Operating Ambient Temperature	-25 to +85	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C

Notes:

1. Tj=25°C to 150°C

2. Repetitive rating: Pulse width limited by maximum junction temperature

3. L=14mH, starting Tj=25°C

4. L=13µH, starting Tj=25°C

Electrical Characteristics (SenseFET part)

(T_A = 25° C unless otherwise specified)

Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	650	-	-	V
		V _{DS} =650V, V _{GS} =0V	-	-	200	μA
I _{DSS}	Zero Gate Voltage Drain Current	Current V_{DS} =520V V_{GS} =0V, T_C =125°C		-	300	μA
R _{DS(ON)}	Static Drain Source On Resistance (1)	V _{GS} =10V, I _D =3.5A	-	1.4	1.6	W
gfs	Forward Transconductance	V _{DS} =40V, I _D =3.5A	-	8	-	mho
Ciss	Input Capacitance			1415	-	
Coss	Output Capacitance	V _{GS} =0V, V _{DS} =25V, f = 1MHz	-	100	-	pF
Crss	Reverse Transfer Capacitance		-	15	-	
td (on)	Turn On Delay Time	n Delay Time		25	-	
tr	Rise Time	V _{DD} =325V, I _D =6.5A ⁽²⁾	-	60	-	nS
td (off)	Turn Off Delay Time		-	115	-	113
tf	Fall Time		-	65	-	
Qg	Total Gate Charge (Gate-Source+Gate-Drain)			40	-	
Qgs	Gate-Source Charge	V _{GS} =10V, I _D =6.5A, V _{DS} =325V ⁽²⁾	-	7	-	nC
Qgd	Gate-Drain (Miller) Charge		-	12	-	

Note:

1. Pulse test: Pulse width \leq 300µS, duty 2% 2. MOSFET switching time is essentially independent of operating temperature.

Electrical Characteristics (Continued)

(T_A=25°C unless otherwise specified)

Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit
UVLO Sect	ion	1	I	1		
V _{START}	Start Threshold Voltage	V _{FB} =GND	14	15	16	V
V _{STOP}	Stop Threshold Voltage	V _{FB} =GND	8	9	10	V
Oscillator S	Section			1		
F _{OSC}	Initial Frequency		18	20	22	kHz
FSTABLE	Voltage Stability	$12V \le V_{CC} \le 23V$	0	1	3	%
∆FOSC	Temperature Stability (1)	$\text{-25}^{\circ}\text{C} \leq T_{A} \leq 85^{\circ}\text{C}$	0	±5	±10	%
DMAX	Maximum Duty Cycle		92	95	98	%
DMIN	Minimum Duty Cycle		-	-	0	%
Feedback S	Section			1		
I _{FBSO}	Feedback Source Current	V _{FB} =GND	0.7	0.9	1.1	mA
I _{FBSI}	Feedback Sink Current	V _{FB} =4V,V _{CC} =19V	2.4	3.0	3.6	mA
V _{SD}	Shutdown Feedback Voltage	V _{FB} ≥ 6.9V	6.9	7.5	8.1	V
Idelay	Shutdown Delay Current	V _{FB} =5V	1.6	2.0	2.4	μA
Protection	Section			1		
V _{OVP}	Over Voltage Protection	$V_{CC} \ge 27V$	34	37	-	V
V _{OCL}	Over Current Latch Voltage (2)		0.95	1.0	1.05	V
TSD	Thermal Shutdown Temp. ⁽¹⁾		140	160	-	°C
Sync & Sof	t-start Section			l		
V _{SS}	Soft start Voltage	V _{FB} =2	4.7	5.0	5.3	V
I _{SS}	Soft start Current	V _{SS} =0V	0.8	1.0	1.2	mA
V _{SH}	Sync High Threshold Voltage	V _{CC} =16V,V _{FB} =5V	6.7	7.2	7.9	V
V _{SL}	Sync Low Threshold Voltage	V _{CC} =16V,V _{FB} =5V	5.4	5.8	6.2	V
-	Section (DPMS Mode)			1		
VBUH	Burst Mode High Threshold Voltage	V _{FB} =0V	11.6	12	12.6	V
VBUL	Burst Mode Low Threshold Voltage	V _{FB} =0V	10.6	11	11.6	V
VBUFB	Burst Mode Enable FB Voltage	V _{CC} =10.5V	0.9	1.0	1.1	V
VBUSS	Burst Mode Enable S_S Voltage	V _{CC} =10.5V,V _{FB} =0V	2.5	3.0	3.5	V
TBUDT	Burst Mode Enable Delay Time	V _{CC} =10.5V,V _{FB} =0V	-	0.5	-	ms
FBU	Burst Mode Frequency	V _{CC} =10.5V,V _{FB} =0V	32	40	48	kHz
Current Lin	nit (Self-Protection) Section		I	1		
IOVER	Peak Current Limit ⁽³⁾		3.52	4.0	4.48	Α
I _{BU PK}	Burst Mode Peak Current Limit		0.45	0.6	0.75	Α
Total Devic	e Section	1		1		
I _{START}	Start Up Current	V _{CC} =Vstart-0.1V	-	40	80	μA
I _{OP}		V _{FB} =GND, V _{CC} =16V				1
I _{OP(MIN)}	Operating Supply Current ⁽⁴⁾	V _{FB} =GND, V _{CC} =12V	-	9	15 r	mA
I _{OP(MAX)}	1	V _{FB} =GND, V _{CC} =27V	-			

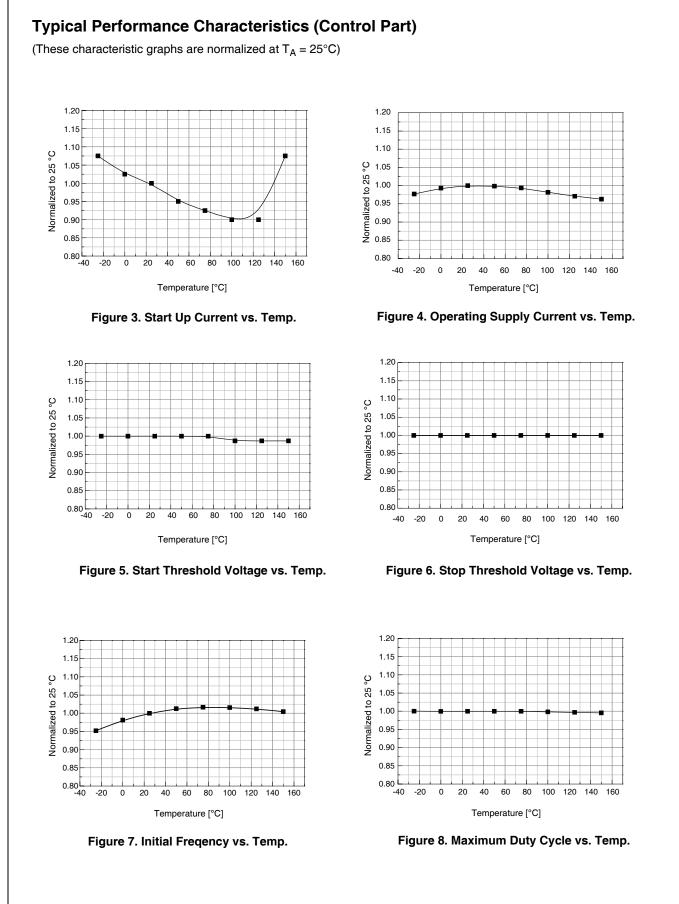
Note:

1. These parameters, although guaranteed at the design, are not tested in mass production.

2. These parameters, although guaranteed, are tested in EDS (wafer test) process.

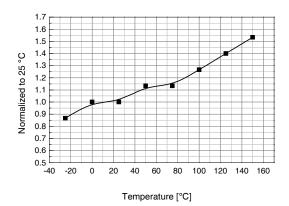
3. These parameters indicate inductor current.

4. These parameters are the current flowing in the control IC.



Typical Performance Characteristics (Continued)

(These characteristic graphs are normalized at T_A = 25°C)



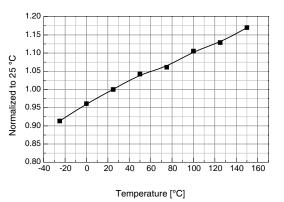


Figure 9. Feedback Offset Voltage vs. Temp.

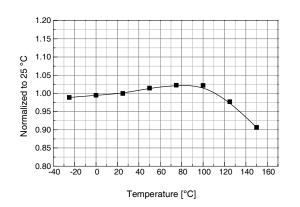


Figure 11. Shutdown Delay Current vs. Temp.

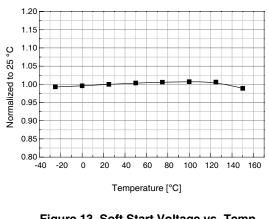


Figure 13. Soft Start Voltage vs. Temp.

Figure 10. Feedback Sink Current vs. Temp.

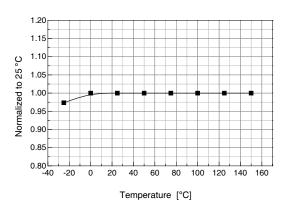
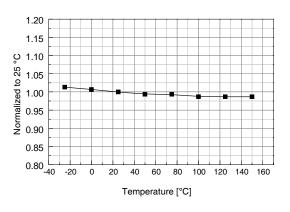
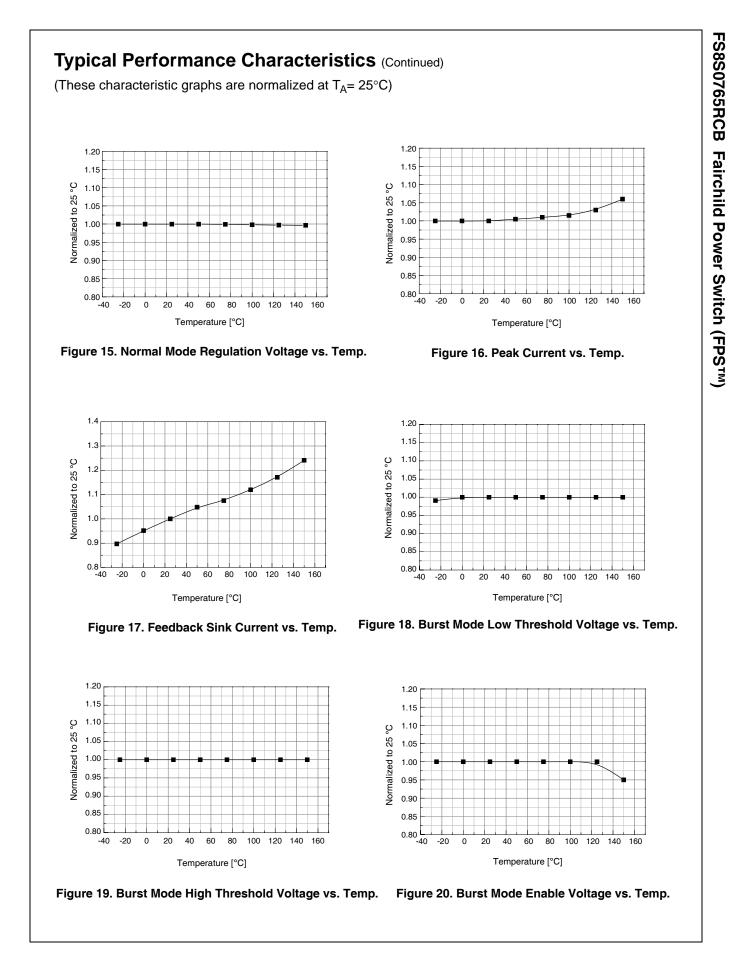


Figure 12. Shutdown Feedback Voltage vs. Temp.



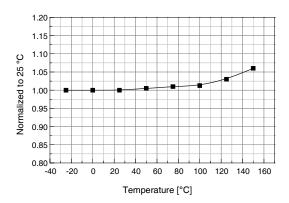






Typical Performance Characteristics (Continued)

(These characteristic graphs are normalized at $T_A{=}\,25^\circ C)$





Functional Description

1. Start up: To guarantee stable operation of the control IC, FS8S0765RCB has UVLO circuit with 6V hysteresis band. Figure 22 shows the relation between the supply current (Icc) and the supply voltage (Vcc). Before Vcc reaches 15V, the FPS consumes only startup current of 80mA, which is usually provided by the DC link through the start-up resistor. When Vcc reaches 15V, the FPS begins operation and the operating current increases to 15mA as shown. Once the control IC starts operation, it continues normal operation until Vcc goes below the stop voltage of 9V.

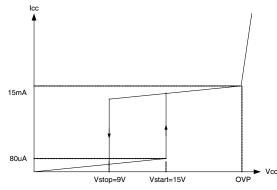
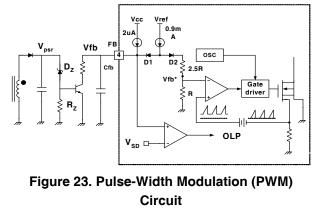


Figure 22. High Voltage Current Source

2. Feedback Control: FS8S0765RCB employs primary side regulation, which permits elimination of feedback circuit components in the secondary side, such as optocoupler and TL431. Figure 23 shows the primary side control circuit. The primary side regulation voltage (Vpsr) is controlled to the breakdown voltage of zener diode (Dz). Because current mode control is employed, the drain current of the power MOSFET is limited by the inverting input of PWM comparator (Vfb*). When MOSFET turns on, usually there exists high current spike in the MOSFET current caused by primary-side capacitance and secondary-side rectifier reverse recovery. To prevent premature termination of the switching pulse due to the current spike, the FPS employs leading edge blanking (LEB). The leading edge blanking circuit inhibits the PWM comparator for a short time after the MOSFET is turned on.



3. Protection function: ES8S0765BCB has four selfprotective functions such as abnormal over current protection (AOCP), overload protection (OLP), overvoltage protection (OVP) and thermal shutdown (TSD). Because these protection circuits are fully integrated into the IC without external components, the reliability can be improved without cost increase. In the event of these fault conditions, the FPS enters into auto-restart operation. Once the fault condition occurs, switching operation is terminated and MOSFET remains off, which forces Vcc to be reduced. When Vcc reaches 9V, the protection is reset and the supply current reduces to 80 µA. Then, Vcc begin to increase with the current provided through the start-up resistor. When Vcc reaches 15V, the FPS resumes normal operation if the fault condition is removed. In this manner, the autorestart alternately enables and disables the switching of the power MOSFET until the fault condition is eliminated, as illustrated in Figure 24.

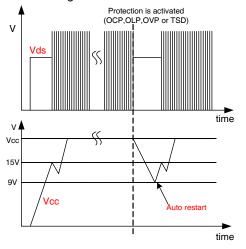
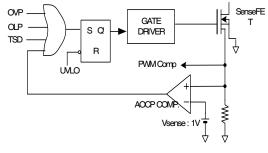


Figure 24. Auto restart operation after protection

3.1 Abnormal Over Current Protection (AOCP): When the secondary rectifying diodes or the transformer pins are shorted, a steep current with extremely high di/dt can flow during the LEB time. Therefore, the abnormal overcurrent protection (AOCP) block is added to ensure the reliability, as shown in Figure 25. It turns off the SenseFET within 300ns after the abnormal over-current condition is sensed.





3.2 Overload Protection (OLP): When the load current exceeds a preset level for longer than the predetermined time, protection circuit should be activated to protect the SMPS. Because of the pulse-by-pulse current limit capability, the maximum peak current through the SMPS is limited, and the maximum input power is restricted with a given input voltage. If the output consumes beyond this maximum power, the output voltage, together with primary side regulation voltage, decrease below the set voltage. This reduces the current through primary side regulation transistor, which increases feedback voltage (Vfb). If Vfb exceeds 2.7V, D1 is blocked and the 2µA current source starts to charge Cfb slowly, compared to when the 0.9mA current source charges Cfb. In this condition, Vfb continues increasing until it reaches 7.5V and the switching operation is terminated at that time, as shown in Figure 27. The delay time for shutdown is the time required to charge Cfb from 2.7V to 7.5V with 2µA.

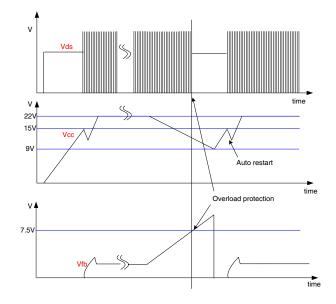
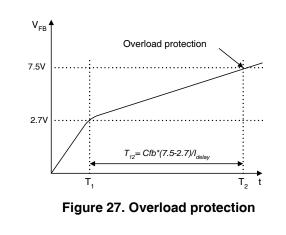


Figure 26. The waveforms at the OLP and auto restart



3.3 Over Voltage Protection (OVP): In case of malfunction in the primary side feedback circuit or feedback loop open caused by a defect of solder, the current through primary side control transistor becomes almost zero. Then, Vfb climbs up in a similar manner to the overload situation, forcing the preset maximum current to be supplied to the secondary side until the over load protection is activated. Because more energy than required is provided to the output, the output voltage may exceed the rated voltage before the over load protection is activated, resulting in the breakdown of the devices in the secondary side. To prevent this situation, an over-voltage protection (OVP) circuit is employed. When the Vcc voltage touches 37V, the OVP block is activated.

3.4 Thermal Shutdown (TSD): The SenseFET and the control IC are built in one package. This allows the control IC to detect the heat generation from the SenseFET. If the temperature exceeds approximately 160°C, the thermal shutdown is activated.

4. Soft Start: Figure 28 shows the soft-start circuit. During the initial start up, the 0.9 mA current source leaks out through Css and Rss. As Css is charged, the leakage current decreases. By choosing much bigger Css than Cfb, it is possible to increase the feedback voltage slowly, forcing the SenseFET current to increase slowly. After Css reaches its steady state value, D3 is blocked and the soft switching circuit is decoupled from the feedback circuit. If the value of Css is too large, there is possibility that Vfb increases to 7.5V, activating the over load protection during soft start time. To avoid this situation, it is recommended that the value of Css should not exceed 100 times the Cfb.

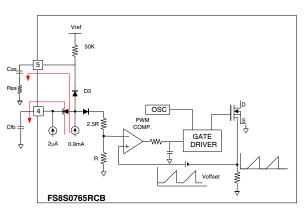


Figure 28. The circuit for the soft start

FS8S0765RCB Fairchild Power Switch (FPS™)

5. Synchronization: To reduce the effect of switching noise on the screen, the SMPS for monitor synchronizes its switching frequency to an external signal, typically the horizontal sync flyback signal. The switching frequency of the FPS can vary from 20 kHz to 150 kHz according to the external sync signal. The internal sync comparator detects the sync signal and determines the SenseFET turn-on time. The SenseFET is turned on at the negative edge of the sync comparator output. The reference voltage of the sync comparator is an inverted saw tooth with a base frequency of 20kHz and a varying range between 5.8V and 7.2V, as shown in the Figure 29. The inverted saw tooth reference gets rid of the excessive switching noise at the first synchronized turn-on. The external sync signal is recommended to have an amplitude higher than 4.2V.

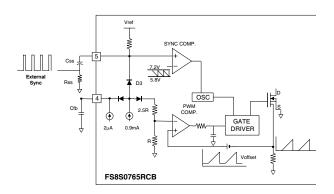


Figure 29. The circuit for the synchronization with external sync

6. Burst mode operation: To minimize the power dissipation at standby mode, FS8S0765RCB has a burst mode operation. In burst mode, the FPS reduces the effective switching frequency and output voltage. The FPS enters burst mode when the voltage of the soft start pin is higher than 3V. No sync signal is applied and the feedback voltage is lower than 1V. During the burst mode operation, Vcc is hysteresis controlled between 11V and 12V. Once the FPS enters burst mode, it stops switching operation until Vcc drops to 11V. When Vcc reaches 11V, the FPS starts switching with switching frequency of 40kHz and peak MOSFET current of 0.6A until Vcc reaches 12V. When Vcc reaches 12V, the switching operation is terminated again until Vcc reduces to 11V. Figure 30 shows operating waveforms. The soft start during the initial start-up is shown in the section 1. During this period, there is no external sync signal and the switching frequency is 20kHz. The section 2 represents the normal mode operation. The switching frequency is synchronized with the external sync signal. In the section 3, the external sync signal is removed; however, the load still exists and the feedback voltage (Vfb) is higher than 1V. In this period, the FPS does the normal switching operation with switching frequency of 20kHz. The section 4 and 5 show the burst mode

operation. At the end of the section 3, the load is eliminated and the feedback voltage (Vfb) drops below 1V, forcing the FPS to stop switching operation. During the section 4, Vcc goes down to 11V. During section 5, Vcc is hysteresis controlled between 11V and 12V. When the external sync signal is applied on the pin 5, the FPS resumes normal operation. To minimize the power consumption in standby mode, it is recommended to set the value of Vcc during normal operation as high as possible (about 29V).

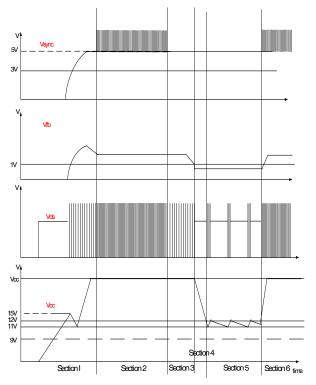
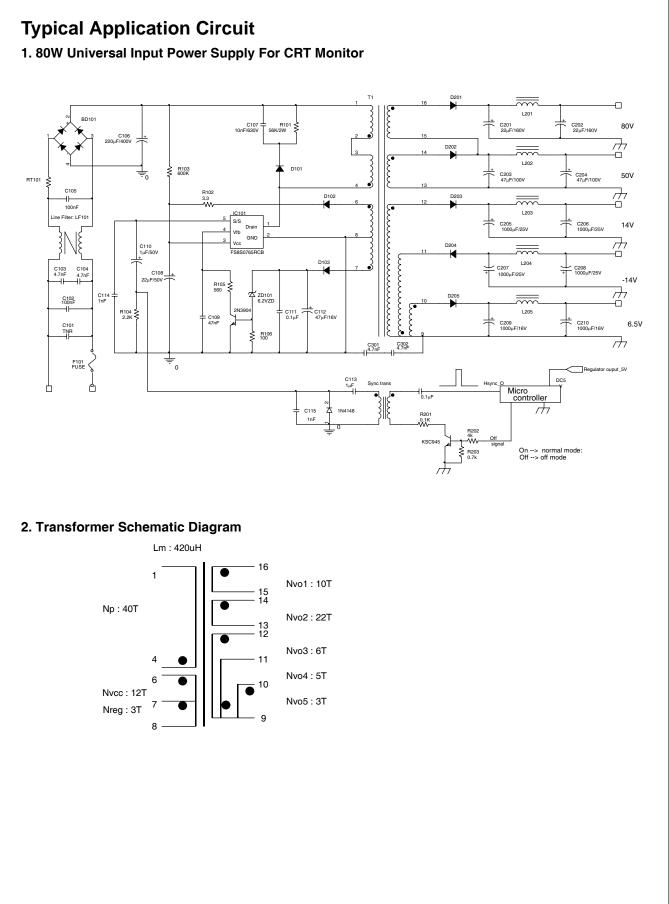


Figure 30. The operation of the FS8S0765RCB at the normal mode and the off mode



3. Winding Specification

No	Pin (s→f)	Wire	Turns	Winding Method
Np1	$4 \rightarrow 1$	$0.3^{\varphi} imes 1$	40	Solenoid Winding
Insulation: P	olyester Tape t = 0.050mm	n, 2 Layers		
Nvo1	$16 \rightarrow 15$	$0.3^{\phi} imes 1$	10	Center Winding
Insulation: P	olyester Tape t = 0.050mm	n, 2 Layers		
Nreg	7 → 8	$0.2^{\varphi} imes 1$	3	Solenoid Winding
Insulation: P	olyester Tape t = 0.050mm	n, 2 Layers		
Nvo2	$14 \rightarrow 13$	$0.3^{\varphi}\times 3$	22	Center Winding
Insulation: P	olyester Tape t = 0.050mm	n, 2 Layers		
Np2	$4 \rightarrow 1$	$0.3^{\varphi} imes 1$	40	Solenoid Winding
Insulation: P	olyester Tape t = 0.050mm	n, 2 Layers		
Nvo3	$12 \rightarrow 9$	$0.3^{\varphi}\times 2$	6	Solenoid Winding
Insulation: P	olyester Tape t = 0.050mm	n, 2 Layers		
Nvo4	$9 \rightarrow 11$	$0.3^{\phi} imes 1$	5	Solenoid Winding
Insulation: P	olyester Tape t = 0.050mm	n, 2 Layers		
Nvo5	$10 \rightarrow 9$	$0.3^{\varphi}\times 2$	3	Solenoid Winding
Insulation: P	olyester Tape t = 0.050mm	n, 2 Layers	· · ·	
Nvcc	$6 \rightarrow 8$	$0.2^{\varphi} imes 1$	12	Solenoid Winding
Outer Insulat	tion: Polyester Tape t = 0.0	50mm, 2 Layers		

4. Electrical Characteristics

	Pin	Specification	Remarks
Inductance	1 - 4	420μH ± 10%	300kHz, 1V
Leakage Inductance	1 - 4	5μH Max	2 nd all short

5. Core & Bobbin

- Core: EER 3540
- Bobbin: EER3540
- Ae(mm2): 107

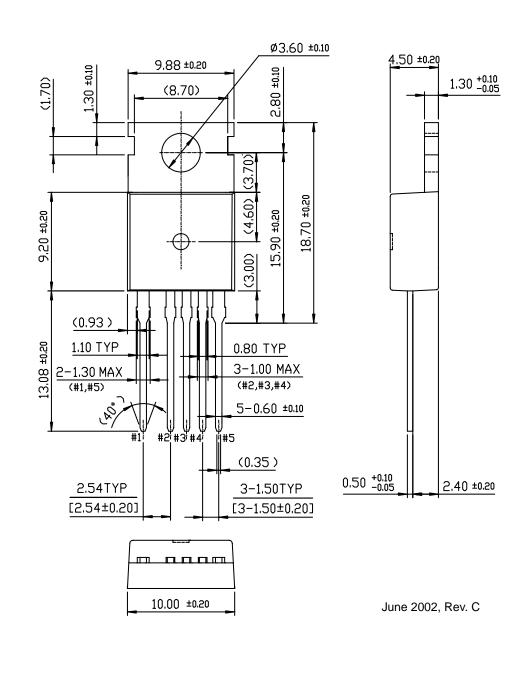
6. Demo Circuit Part List

Part	Value	Note	Part	Value	Note
	Fuse		C201	22nF/160V	Electrolytic Capacitor
F101	3A/250V		C202	22nF/160V	Electrolytic Capacitor
	NTC		C203	47nF/100V	Electrolytic Capacitor
RT101	10D-9		C204	47nF/100V	Electrolytic Capacitor
Resistor		C205	1000nF/25V	Electrolytic Capacitor	
R101	56k Ω	2W	C206	1000nF/25V	Electrolytic Capacitor
R102	3.3Ω	1/4W	C207	1000nF/25V	Electrolytic Capacitor
R103	600kΩ	1W	C208	1000nF/25V	Electrolytic Capacitor
R104	2.2k Ω	1/4W	C209	1000nF/25V	Electrolytic Capacitor
R105	0.56kΩ	1/4W	C210	1000nF/25V	Electrolytic Capacitor
R106	0.1kΩ	1/4W	C211	0.1µF/50V	Ceramic Capacitor
R201	0.1kΩ	1/4W	C301	4.7nF	AC Filter Capacitor
R202	4k Ω	1/4W	C302	4.7nF	AC Filter Capacitor
R203	0.7kΩ	1/4W			
			Sync trans	22mH	
	Inducto	r			
L201 ~ L205	13uH				
				Dio	ode
			D101	UF4007	
	Capacite	or	D102	TVR10G	
C101	471D10	TNR	D103	TVR10G	
C102	100nF	Box Capacitor	D201	UF4007	
C103	4.7nF	AC Filter Capacitor	D202	UF5404	
C104	4.7nF	AC Filter Capacitor	D203	UF5402	
C105	100nF	Box Capacitor	D204	UF5402	
C106	220µF/400V	Electrolytic Capacitor	D205	UF5401	
C107	10nF/630V	Ceramic Capacitor			
C108	22µF/50V	Electrolytic Capacitor	BD101	KBL406	Bridge Diode
C109	47nF/50V	Ceramic Capacitor		Line	Filter
C110	1μF/50V	Electrolytic Capacitor	LF101	24mH	
C111	0.1µF/50V	Ceramic Capacitor		IC	<u> </u>
C112	47μF/50V	Electrolytic Capacitor	IC101	FS8S0765RC	(7A, 650V)
C113	1μF/50v	Electrolytic Capacitor	IC201	KSC945	NPN Transistor
C114	1nF/50V	Ceramic Capacitor			
C115	1nF/50V	Ceramic Capacitor			

Package Dimensions

TO-220-5L

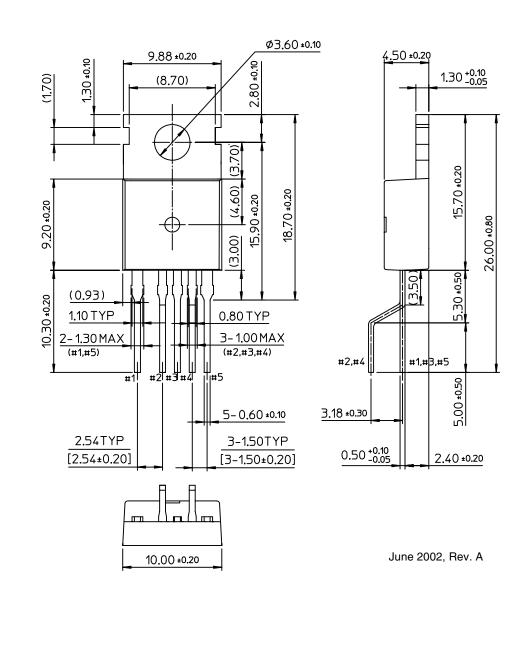
Dimensions in millimeters



Package Dimensions (Continued)

TO-220-5L (Forming)

Dimensions in millimeters



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PRODUCT STATUS DEFINITIONS Definition of Terms

Datasheet Identification	Product Status	Definition
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